

Vertical GaN: Breakthrough for AI & Automotive Electrification

Subhash Pidaparthi

*Vertical GaN R&D Leader
onsemi*

**Bodo's
Wide Bandgap
Event 2025**

Making WBG Designs Happen

GaN



Vertical GaN: Breakthrough for AI & Automotive Electrification

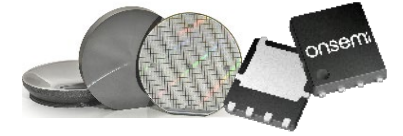
Subhash Pidaparthi
GaN Business Unit

December 3rd, 2025

© onsemi 2025 | Public Information



onsemi enters the GaN market!

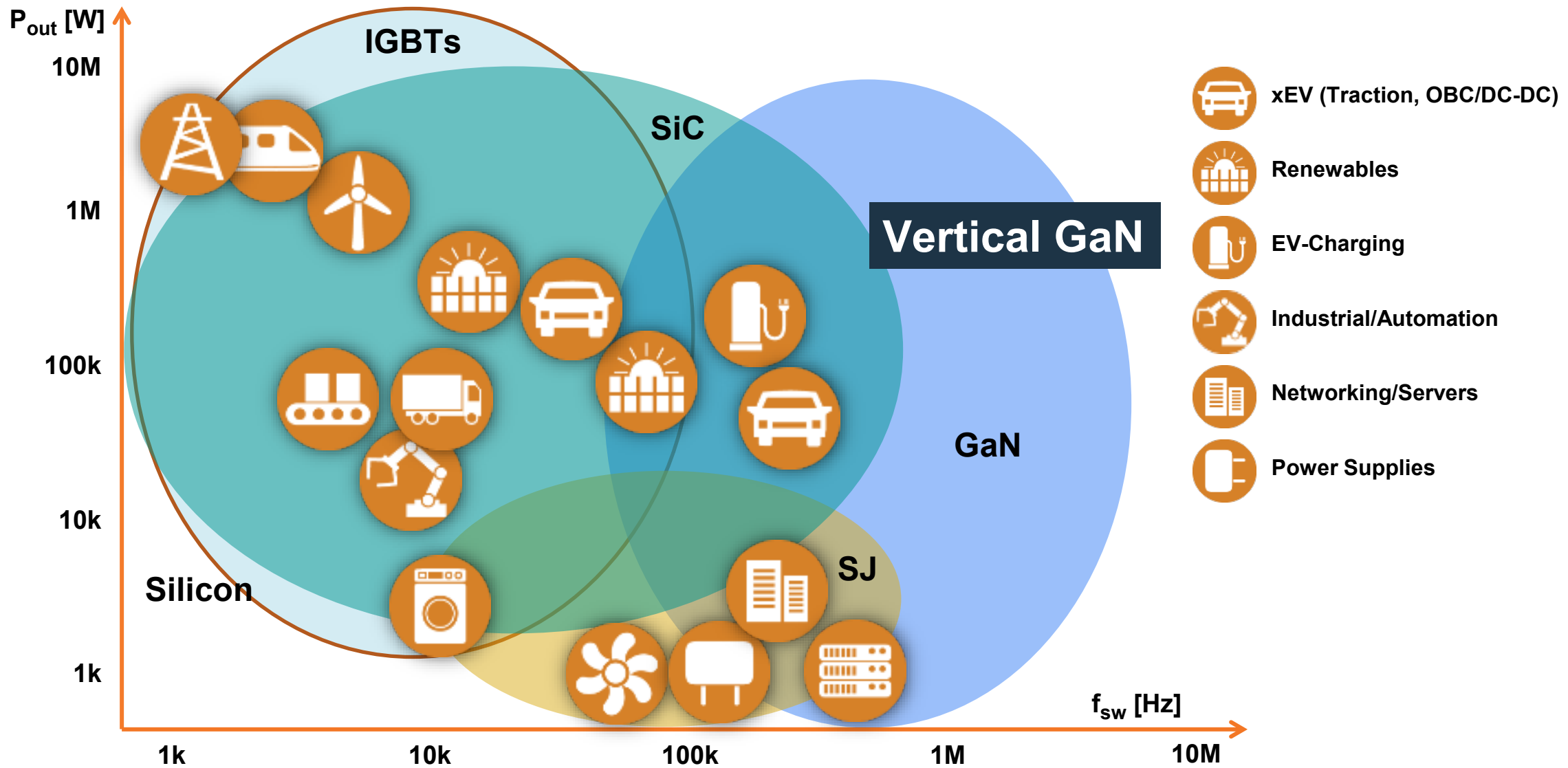


- onsemi is offering **ALL key power electronics technologies**: Si, SiC & GaN
- For UHV (>1200V) applications **onsemi innovates with Vertical GaN device**
- Acquired in 2024 from **NexGen Power Systems**, **Vertical GaN IP** is being integrated into **onsemi** manufacturing operations:
 - Proven & resilient supply chain
 - Quality & reliability
 - Manufacturing to scale



Process running in onsemi Fab (Syracuse, USA)
Sampling to Key Partners. Expanding in H2'26!

Power Switching Technologies for Various Applications



vGaN Architecture – Compact and Robust Device



1 Basic Function of a Switch

Gate action causes switching

OFF
Gate closed
no current

ON
Gate open
Current flow

Current flows from
Drain to Source

3 3D Roadmap

- Increased area for increased current
- Thicker growth for higher voltage
- Uses all three dimensions to create product roadmap

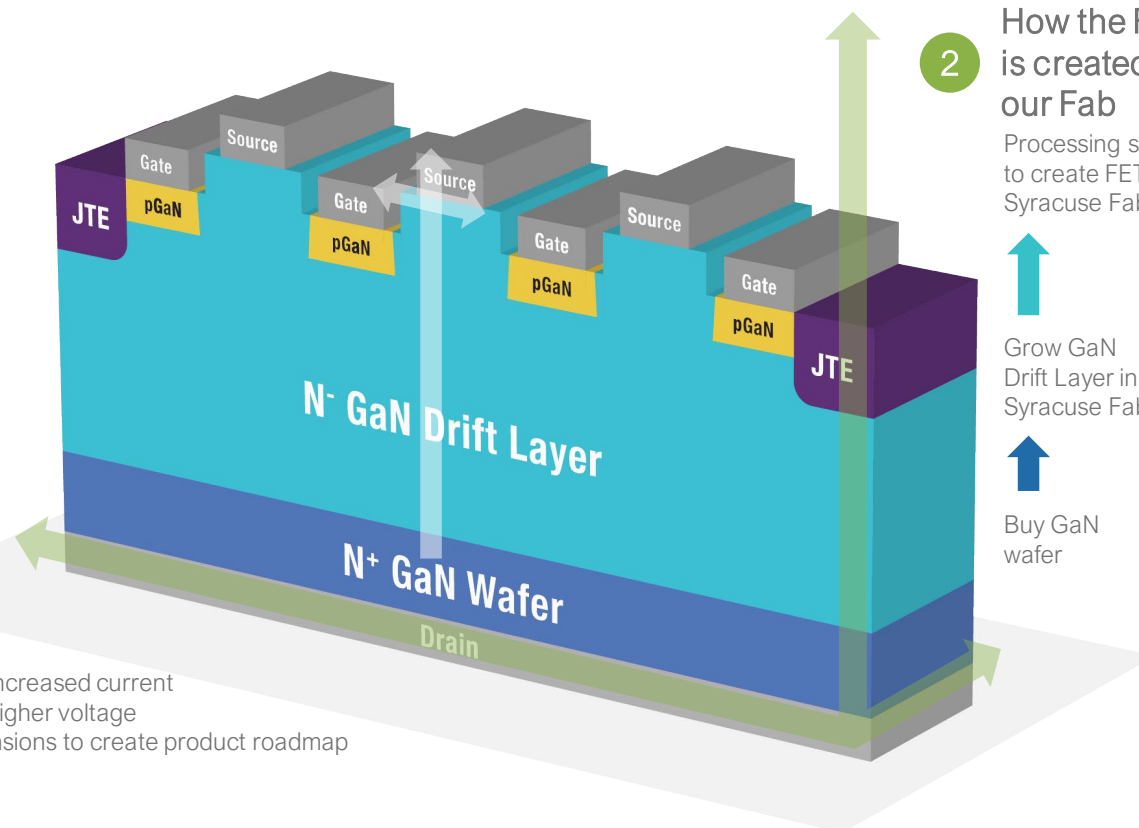
2

How the FET is created in our Fab

Processing steps to create FET in Syracuse Fab

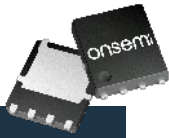
Grow GaN Drift Layer in Syracuse Fab

Buy GaN wafer

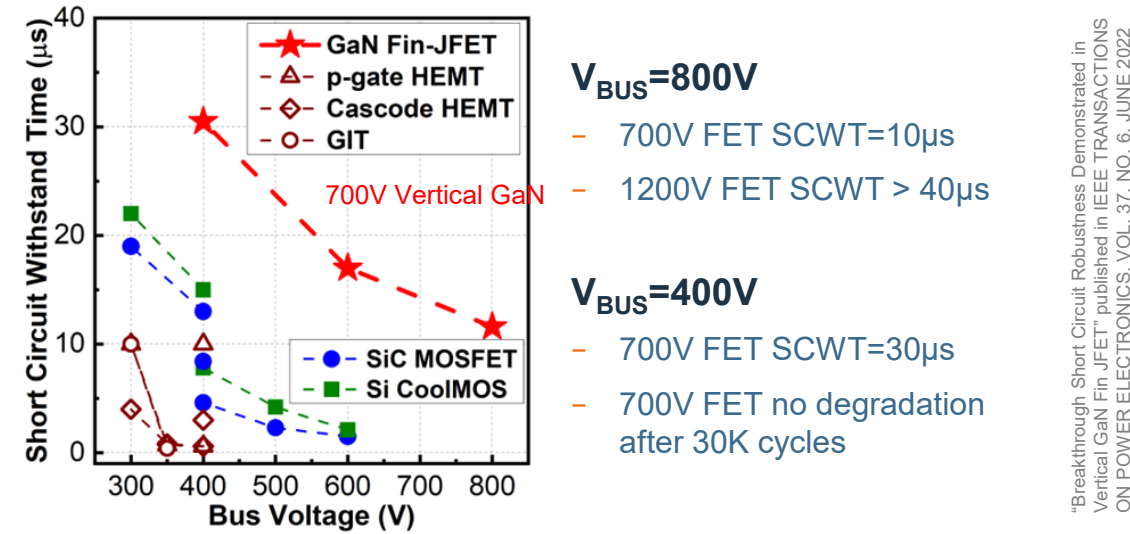


- Vertical GaN-on-GaN provides a scalable, high conductivity, Normally-OFF power switch
- Channel utilizes high bulk GaN mobility to achieve ultra low $R_{DS,ON}$ with no dynamic variation
- Device structure enables robust edge termination for full avalanche capability

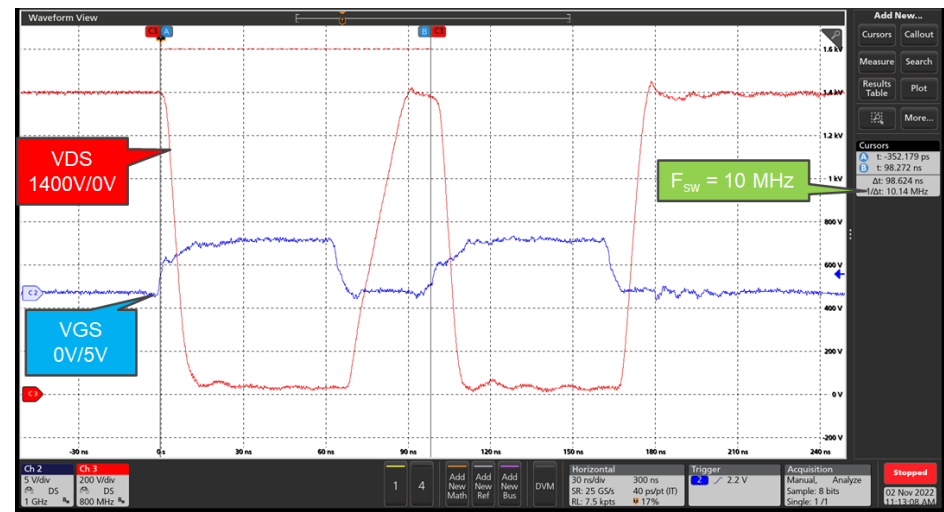
vGaN Performance – Setting new benchmark



Best-in-class Short-Circuit Ruggedness



Fast Switching: 1.4kV at 10 MHz



Edwards, Andrew, et al. "Switching of a Bus Voltage of 1400 V at 10 MHz Using Vertical GaN Fin-JFETs." 2023 35th International Symposium on Power Semiconductor Devices and ICs (ISPSD). IEEE, 2023.

Repetitive Avalanche

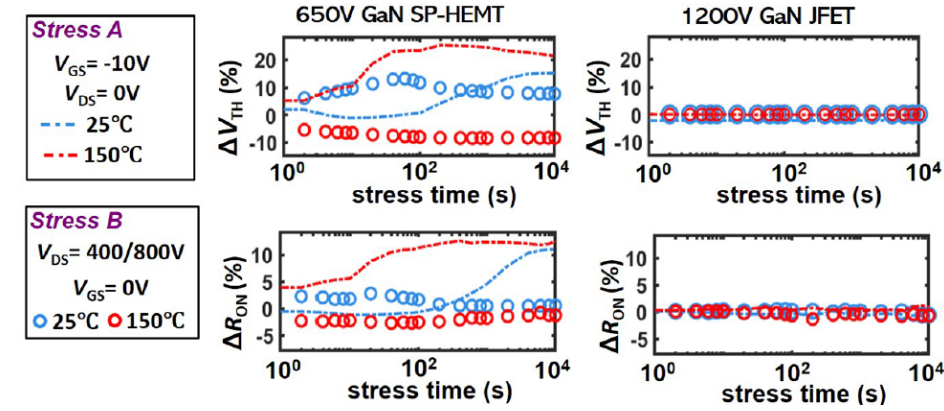
Device	Voltage Rating (kV)	E_{AVA} (J/cm ²)	Repetitive Avalanche			Failure signature
			$E_{\text{AVA}}\%$ ^a	Period	Cycle survived	
GaN Fin JFET	0.65	10.0	70%	3 s	>3700*	FTO
Si CoolMOS	0.6-0.9	1.3 [22]	62% [8]	3 s	10000	FTS
SiC JFET ^b	1.2	18 [10]	90% [10]	4 s	1000	FTS
SiC MOSFET	1.2	7.5 ^c [4]	<77% ^d [6]	0.5 s	80000	FTS

FTO = Failure to open. The device maintains blocking voltage after failure.
FTS = Failure to short.

* >1M cycles at 20% of E_{AVA}

Zhang, Ruizhe, et al. "Robust through-fin avalanche in vertical GaN Fin-JFET with soft failure mode." IEEE Electron Device Letters 43.3 (2022): 366-369.

No Dynamic $R_{\text{DS,ON}}$ Variation with V_{T} Stability

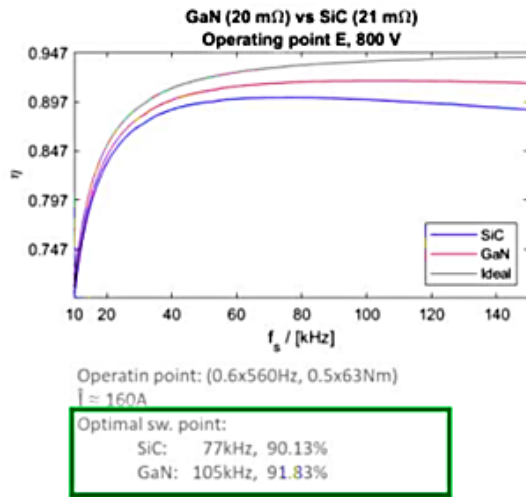
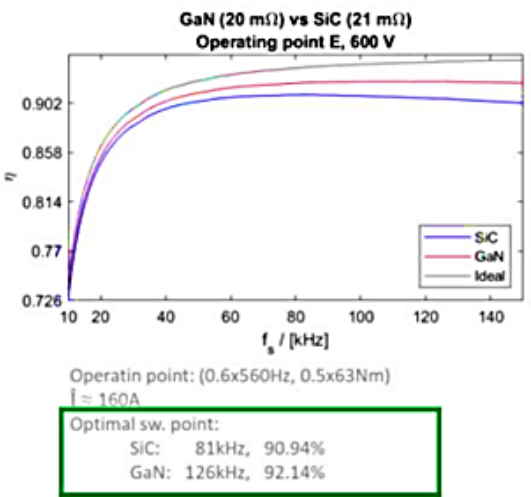
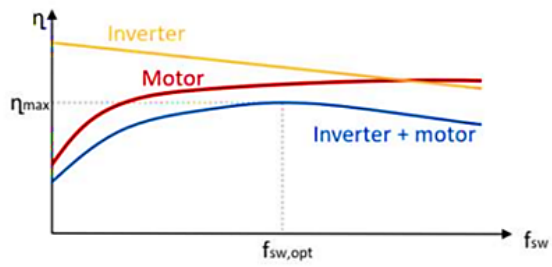


Application – Next level of power density and performance



EV Traction: next-level of System Efficiency

- Optimal Inverter Switching Frequency improves E-drive Efficiency
- With lowest switching losses, vGaN improves System Efficiency by ~2%



Efficiency Improvement of Induction Machine Powertrain by High Switching Frequency and Wide Bandgap Semiconductors
IEEE PEDS 2023, Montreal, Canada , 7 – 10 August 2023

800V

AI Server: power density ↑ , complexity ↓

- Vertical power delivery → Highest power density and best system-level thermal management
- BOM reduction and simpler control vs 3-level or stacked topologies

Multilevel converter with 650V GaN

- + Higher* power density
- + Smaller* magnetics and capacitors
- Complex

* vs. B6/2L 1200V SiC

3 phase B6/2L with 1200V vGaN

- + Highest power density and Efficiency
- + Simplest



Intelligent Technology. Better Future.

<https://www.onsemi.com/solutions/technology/vertical-gan>

Follow us @onsemi



[onsemi.com](https://www.onsemi.com)